

N75

Product Specifications

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This document provides a guide for users to use N75.

This document is intended for system engineers (SEs), development engineers, and test engineers.

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About This Document

Scope

This document is applicable to the N75 series.

It defines the features, indicators, and test standards of the N75 module and provides reference for the hardware design of each interface.




Audience

This document is intended for [system engineers \(SEs\)](#), [development engineers](#), and [test engineers](#).

Change History

| Issue | Date | Change | Changed By |
|-------|---------|---|-------------------|
| 1.0 | 2019-03 | Initial draft | Wang Qiang |
| 1.1 | 2019-08 | <ul style="list-style-type: none">Deleted Band14 of N75-NA and N75-AUpdated the label of moduleChanged the Variant E to EAAdded the Variant NFUpdated the document template | Zhuo Jianzheng |

Conventions

| Symbol | Indication |
|---|---|
|  | Means danger. You are in a situation that could cause fatal device damage or even bodily damage. |
|  | Means the reader be careful. In this situation, you might perform an action that could result in module or product damages. |
|  | Means note or tips for readers to use the module |

Related Documents

Neoway_N75_Datasheet

Neoway_N75_Product_Specifications

Neoway_N75_AT_Command_Mannual

Neoway_N75_EVK_User_Guide

Neoway Module Reflow Manufacturing Recommendations

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1 About N75

N75 is an industrial-grade 4G module developed on a Qualcomm platform. It supports GSM/GPRS/EDGE, WCDMA R99 to DC-HSPA+, and LTE Cat4. With various hardware interfaces and optional GNSS functions, the N75 is well applicable to wireless metering terminals, in-vehicle terminals, POS, industrial routers, and other IoT terminals.

1.1 Product Overview

N75 series include multiple variants. Table 1-1 lists the variants and frequency bands supported.

Table 1-1 Variant and frequency bands

| Variant | Region | Category | Band | GNSS ¹ |
|---------|----------------|----------|---|-------------------|
| NA | North America | Cat4 | FDD-LTE: B2, B4, B5, B7, B12, B13, B25, B26, B66, B71 UMTS: B2, B4, B5 GSM/GPRS/EDGE: 850/1900 MHz | support |
| NF | North America | Cat4 | FDD-LTE: B2, B4, B5, B7, B12, B13, B14, B25, B26, B66, B71 UMTS: B2, B4, B5 GSM/GPRS/EDGE: 850/1900 MHz | |
| A | North America | Cat4 | FDD-LTE: B2, B4, B5, B12, B66 UMTS: B2, B4, B5 | support |
| EA | European Union | Cat4 | FDD-LTE: B1, B3, B5, B7, B8, B20, B28 TDD-LTE: B38, B40 UMTS: B1, B5, B8 GSM/GPRS/EDGE: 900/1800 MHz | support |
| JP | Japan | Cat4 | FDD-LTE: B1, B3, B8, B18, B19, B26 TDD-LTE: B41 UMTS: B1, B6, B8, B19 | support |

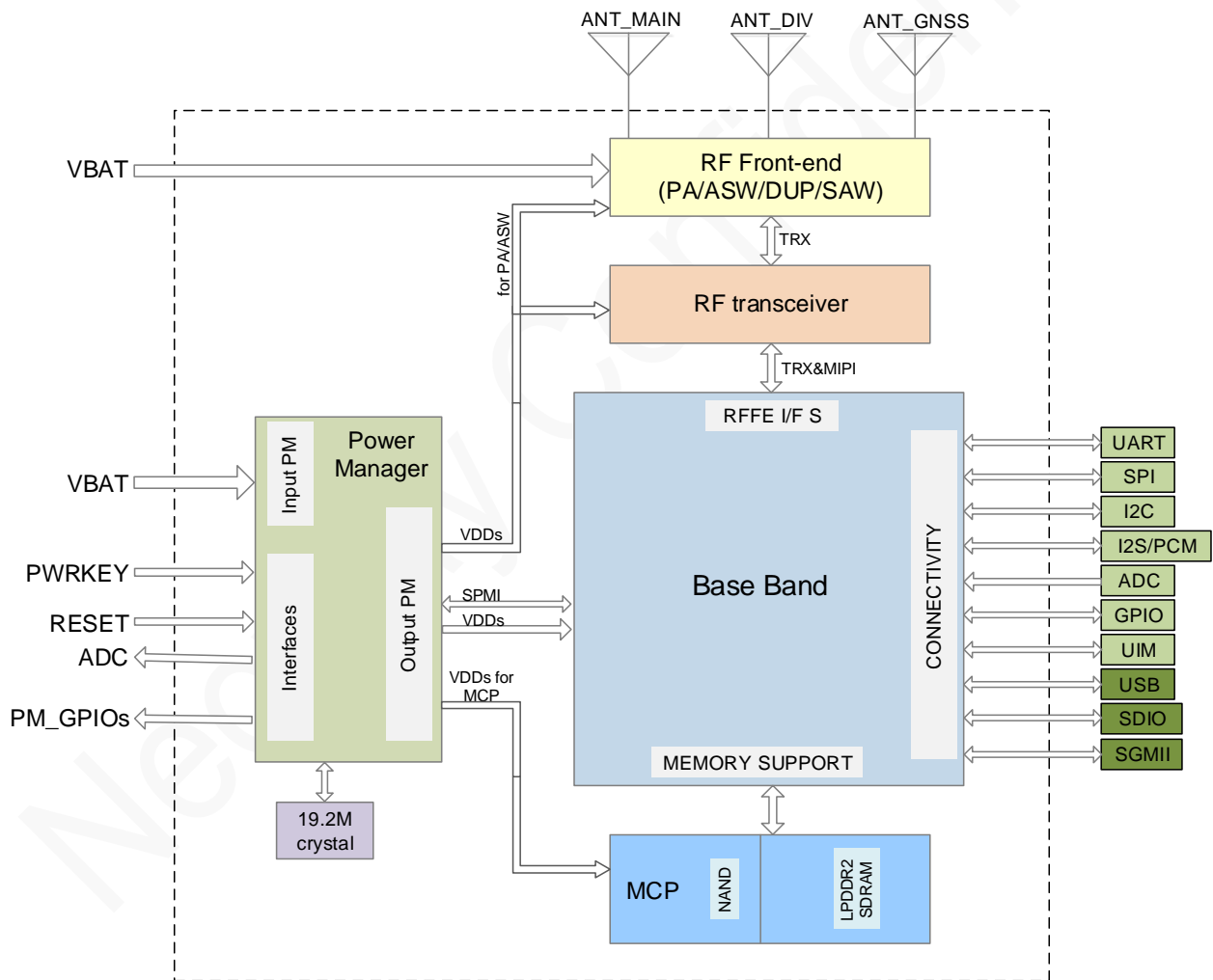
¹ GNSS optional for all above variants

1.2 Block Diagram

N75 consists of the following functionality units:

- Baseband
- MCP
- Power management unit
- 19.2MHz crystal oscillator
- RF section
- Digital interfaces (UIM, SPI, I2C, SGMII, SDIO, ADC, GPIO, UART, USB)

Figure 1-1 Block Diagram



1.3 Basic Features

| Parameter | Description |
|------------------------|--|
| Physical features | Dimensions: (30.0±0.1) mm × (28.0±0.1) mm × (2.8±0.15) mm Package: 100-pin LGA Weight: around 5.3g |
| Temperature ranges | Operating: -35°C to +75°C Extended: -40°C to +85°C Storage: -45°C to +90°C |
| Operating voltage | VBAT: 3.3V to 4.3V, TYP: 3.8V |
| Current | Flight mode 1.24 mA |
| | Sleep Mode GSM DRX=6: 2.2 mA GSM DRX=9: 1.45 mA WCDMA DRX=2: 2.64 mA WCDMA DRX=9: 1.54 mA LTE (Paging Cycle 320ms): 6.5 mA LTE (Paging Cycle 2.56s): 1.67 mA |
| | Active VBAT: 2A Max |
| MIPS processor | ARM Cortex-A7 microprocessor cores at 1.3 GHz |
| Memory | ROM+RAM: <ul style="list-style-type: none"> • 2Gb+1Gb • 4Gb+2Gb |
| Operating Bands | See Table 1-1. |
| Wireless rate | GPRS: Max 85.6 Kbps(DL) / Max 85.6 Kbps(UL) EDGE: Max 236.8Kbps(DL) / Max 236.8Kbps(UL) WCDMA: DC-HSPA+, Max 42Mbps (DL)/Max 5.76 Mbps (UL) FDD-LTE: non-CA cat4, Max 150 Mbps(DL)/Max 50 Mbps (UL) |
| Transmit power | GSM850: (33dBm±2dB) (Power Class 4) GSM900: (33dBm±2dB) (Power Class 4) DCS1800: (30dBm±2dB) (Power Class 1) PCS1900: (30dBm±2dB) (Power Class 1) EDGE 850MHz: (27dBm±3dB) (Power Class E2) EDGE1900MHz: (26dBm±3dB) (Power Class E2) UMTS: (24dBm+1/-3dB) (Power Class 3) LTE: (23dBm±2dB) (Power Class 3) |
| Application Interfaces | 2G/3G/4G antenna interface, diversity antenna interface, GNSS antenna interface 50Ω impedance Two UART interfaces: one is an ordinary serial port, and one is used for Bluetooth by default |

| | |
|------------------------|--|
| | One I2C interface, supporting only host mode |
| | One SPI interface, supporting only host mode and max. 50 MHz |
| | One USIM interface, 1.8V/3V |
| | One USB2.0 interface, OTG function requires external 5V DC-DC |
| | Two 15-bit ADC interfaces, detectable voltage ranging from 0.1 to 1.7V |
| | One I2S/PCM interface, to connect CODEC chipset |
| | One SDIO interface, used for WLAN |
| | One SGMII/MDIO interface, used for Ethernet |
| | Four GPIO interfaces |
| AT command | Neoway extended commands |
| Data | PPP, RNDIS, ECM, RMNET |
| Protocol | TCP, UDP, MQTT, FTP/FTPS, HTTP/HTTP(S), SSL, TLS |
| Certification approval | FCC, PTCRB, AT&T*, CE-R*, GCF*, RoHS*, NCC*, RCM* |

2 Compliant Standards

- 3GPP TS 07.07AT command set for GSM Mobile Equipment (ME)
- YD 1214-2006 Technical requirement of 900/1800MHz TDMA Digital Cellular Mobile Telecommunication Network General Packet Radio Service (GPRS)Equipment: Mobile Stations
- YD 1215-2006Testing Methods of 900/1800MHz TDMA Digital Cellular Mobile Telecommunication Network General Packet Radio Service (GPRS)Equipment: Mobile Stations
- YD 1032-2000Limits and Measurement Methods of Electromagnetic Compatibility for 900/1800MHz Digital Cellular Telecommunications System Part1: Mobile Station and Ancillary Equipment
- YD/T 2220-2011 Technical Requirement and test method of WCDMA/GSM(GPRS) dual-mode digit mobile user equipment (phase 4)
- Ministry of Industry and Information Technology PRC, Measures for the Network Access Management of Telecommunication Equipment (2014 Amendment)
- GB4943.1-2011 Information technology equipment - Safety - Part 1: General requirements
- GB/T22450.1-2008 Limits and measurement methods of electromagnetic compatibility for 900/1800MHz TDMA digital cellular telecommunications system - Part 1: Mobile station and ancillary equipment
- CNCA-O7C-031:2007Rules for Compulsory Certification of Telecommunication Equipment Telecommunication Terminal Equipment
- 3GPP TS GSM Specification Set
- 3GPP TS WCDMA Specification Set
- 3GPP TS LTE Cat4 4G Specification Set

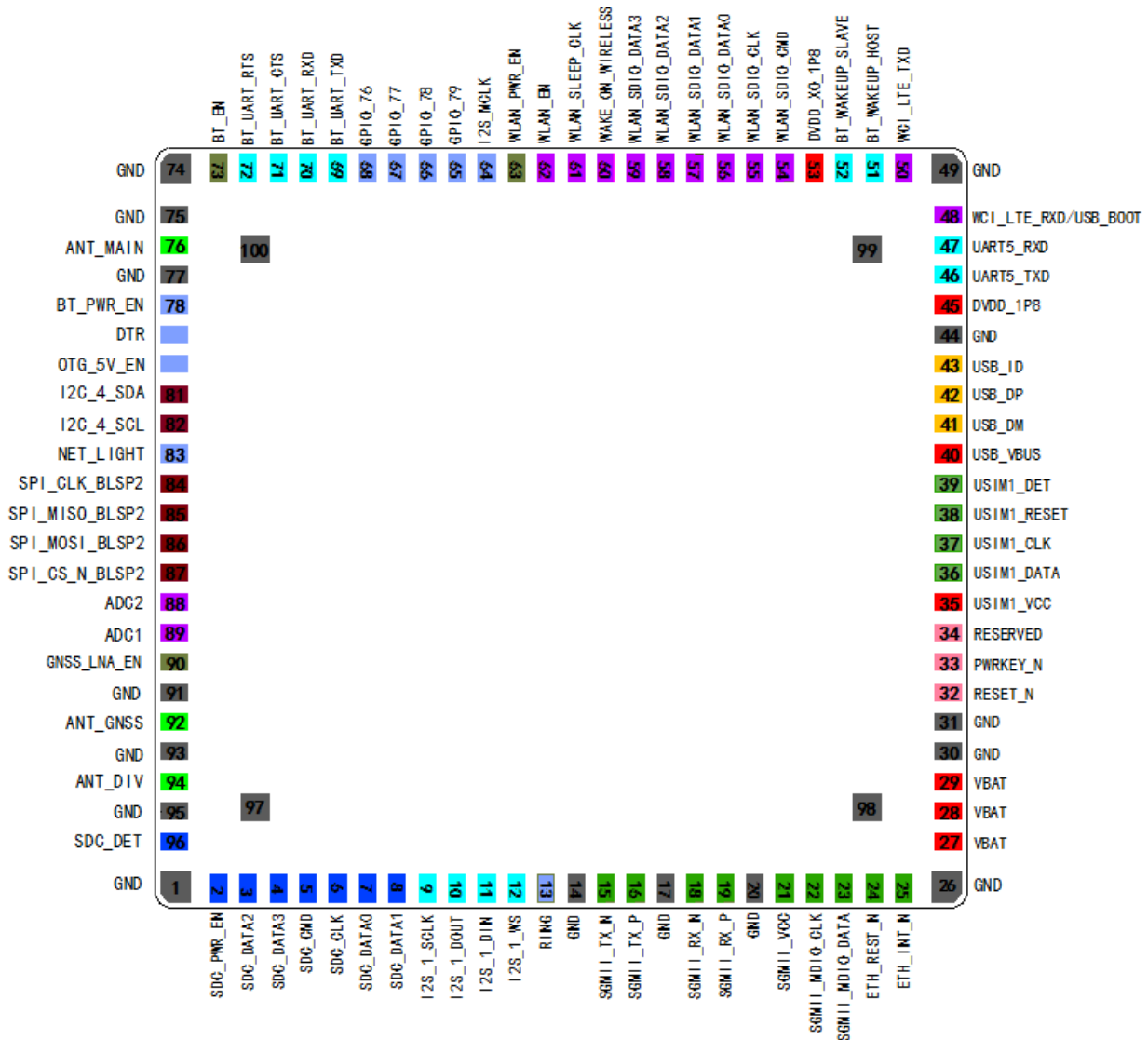
3 Pins and Appearance

There are 100 pins on N75 and their pads are introduced in the LGA package.

3.1 Pad Layout

Figure 2-1 shows the pad layout of the N75.

Figure 3-1 N75 pin definition (Top View)

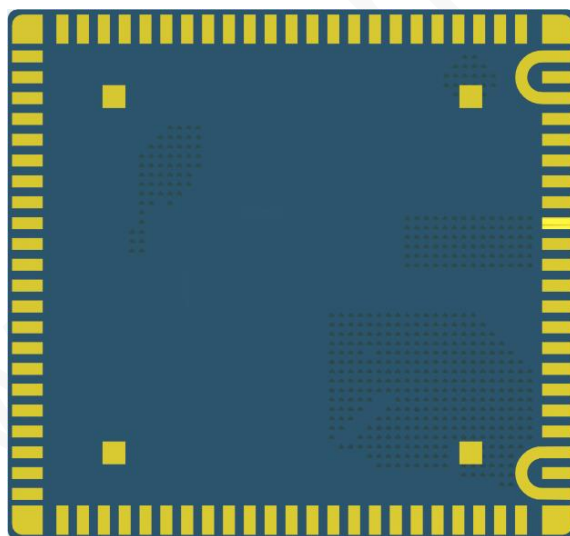


3.2 Appearance

Figure 3-1 Top view of the N75



Figure 3-1 Bottom view of the N75



Label in the above figure indicates the N75 NA variant. Labels of other variants are similar.

4 Electric Feature and Reliability

This chapter describes the electric features and reliability of N75, including the current and voltage of each power pin, operating and storage temperature ranges, and ESD protection features.

4.1 Electric Features

Table 4-1 Electric features

| Parameter | | Minimum Value | Typical Value | Maximum Value |
|-----------|----------|---------------|---------------|---------------|
| VBAT | V_{in} | 3.3V | 3.8V | 4.3V |
| | I_{in} | / | / | 2A |



- If the voltage is lower than the threshold, the module might fail to start. If the voltage is higher than the threshold or there is a voltage burst during the startup, the module might be damaged permanently.
- If you use LDO or DC-DC to supply power for the module, ensure that it outputs at least 2 A current. When the module works at maximum power in GSM mode, the peak current might reach 2A. Add a large capacitor to the VBAT pin to enhance the capability to output continuous current and avoid voltage drop.

Table 4-2 Current consumption of N75

| Status | Test Conditions | Test Result (Typ) | Unit |
|-------------|--------------------------|-------------------|---------|
| Power OFF | Shut down the module. | 20 | μ A |
| | GSM850 DRX=2 | 2.81 | mA |
| | GSM850 DRX=9 | 1.45 | mA |
| | WCDMA DRX=2 | 2.64 | mA |
| Sleep Mode | LTE Paging cycle = 320ms | 6.5 | mA |
| | LTE Paging cycle = 640ms | 3.8 | mA |
| | LTE Paging cycle = 1.28s | 2.4 | mA |
| | LTE Paging cycle = 2.56s | 1.67 | mA |
| Active Mode | GSM850 Voice Call PCL=5 | 248 | mA |
| | GSM1900 Voice Call PCL=0 | 172 | mA |
| | GPRS850 1DL/4UL PCL=5 | 394 | mA |

| | | |
|------------------------------|-----|----|
| GPRS1900 1DL/4UL PCL=0 | 346 | mA |
| EGPRS850 1DL/4UL PCL=8 | 418 | mA |
| EGPRS1900 1DL/4UL PCL=2 | 436 | mA |
| WCDMA Band2@ Max Tx power | 464 | mA |
| WCDMA Band4@ Max Tx power | 560 | mA |
| WCDMA Band5@ Max Tx power | 421 | mA |
| LTE-FDD Band1@ Max Tx power | 500 | mA |
| LTE-FDD Band2@ Max Tx power | 495 | mA |
| LTE-FDD Band3@ Max Tx power | 550 | mA |
| LTE-FDD Band4@ Max Tx power | 572 | mA |
| LTE-FDD Band5@ Max Tx power | 441 | mA |
| LTE-FDD Band7@ Max Tx power | 570 | mA |
| LTE-FDD Band8@ Max Tx power | 440 | mA |
| LTE-FDD Band12@ Max Tx power | 534 | mA |
| LTE-TDD Band13@ Max Tx power | 416 | mA |
| LTE-TDD Band14@ Max Tx power | 517 | mA |
| LTE-FDD Band18@ Max Tx power | TBD | mA |
| LTE-FDD Band19@ Max Tx power | TBD | mA |
| LTE-FDD Band20@ Max Tx power | TBD | mA |
| LTE-TDD Band25@ Max Tx power | 480 | mA |
| LTE-TDD Band26@ Max Tx power | 462 | mA |
| LTE-FDD Band28@ Max Tx power | TBD | mA |
| LTE-TDD Band66@ Max Tx power | 539 | mA |
| LTE-TDD Band71@ Max Tx power | 530 | mA |

4.2 Temperature Features

Table 4-3 Temperature features

| Status | Minimum Value | Typical Value | Maximum Value |
|---------------------|---------------|---------------|---------------|
| Operating | -35°C | 25°C | 75°C |
| Extended | -40°C | | 85°C |
| Storage temperature | -45°C | | 90°C |



If the module works in an environment of -35°C to -40°C or 75°C to 85°C, RF performance might be worse. This does not affect the running of the module. The RF performance will meet the 3GPP standard after the temperature reaches the operating range.

4.3 ESD Protection

Electronics need to pass ESD tests. Table 4-4 shows the ESD capability of key pins of this module. It is recommended to add ESD protection based on the application scenarios to ensure product quality when designing a product.

Humidity 45% Temperature 25°C

Table 4-4 ESD protection features

| Testing Point | Contact Discharge | Air Discharge |
|---------------|-------------------|---------------|
| VBAT | ±8kV | ±15kV |
| GND | ±8kV | ±15kV |
| ANT | ±8kV | ±15kV |
| Cover | ±8kV | ±15kV |
| Others | ±2kV | ±4kV |

5 RF Features

N75 supports 2G/3G/4G network modes and frequency bands as well as GNSS function. This chapter describes the RF features of N75.

5.1 Operating Bands

Table 5-1 Operating Bands

| Operating Bands | Uplink | Downlink |
|-----------------|--------------|--------------|
| GSM850 | 824~849MHz | 869~894MHz |
| GSM900 | 880~915MHz | 925~960MHz |
| DCS1800 | 1710~1784MHz | 1805~1880MHz |
| PCS1900 | 1850~1910MHz | 1930~1990MHz |
| UMTS B1 | 1920~1980MHz | 2110~2170MHz |
| UMTS B2 | 1850~1910MHz | 1930~1990MHz |
| UMTS B4 | 1710~1755MHz | 2110~2155MHz |
| UMTS B5 | 824~849MHz | 869~894MHz |
| UMTS B6 | 830~840MHz | 875~885MHz |
| UMTS B8 | 880~915MHz | 925~960MHz |
| UMTS B19 | 830~845MHz | 875~890MHz |
| FDD-LTE B1 | 1920~1980MHz | 2110~2170MHz |
| FDD-LTE B2 | 1850~1910MHz | 1930~1990MHz |
| FDD-LTE B3 | 1710~1785MHz | 1805~1880MHz |
| FDD-LTE B4 | 1710~1755MHz | 2110~2155MHz |
| FDD-LTE B5 | 824~849MHz | 869~894MHz |
| FDD-LTE B7 | 2500~2570MHz | 2620~2690MHz |
| FDD-LTE B8 | 880~915MHz | 925~960MHz |
| FDD-LTE B12 | 699~716MHz | 728~746MHz |
| FDD-LTE B13 | 777~787MHz | 746~757MHz |
| FDD-LTE B14 | 788~798MHz | 758~768MHz |

| | | |
|-------------|--------------|--------------|
| FDD-LTE B18 | 815~830MHz | 860~875MHz |
| FDD-LTE B19 | 830~845MHz | 875~890MHz |
| FDD-LTE B20 | 832~862MHz | 791~821MHz |
| FDD-LTE B25 | 1850~1915MHz | 1930~1995MHz |
| FDD-LTE B26 | 814~849MHz | 859~894MHz |
| FDD-LTE B28 | 703~748MHz | 758~803MHz |
| FDD-LTE B66 | 1710~1780MHz | 2110~2200MHz |
| FDD-LTE B71 | 617~652MHz | 663~698MHz |

5.2 TX Power and RX Sensitivity

Table 5-2 RF TX power

| Band | TX Power | RX Sensitivity |
|------------|----------------|----------------|
| GSM850 | 33dBm+2/-2dBm | <-108dBm |
| GSM900 | 33dBm+2/-2dBm | <-108dBm |
| DCS1800 | 30dBm+2/-2dBm | <-108dBm |
| PCS1900 | 30dBm+2/-2dBm | <-108dBm |
| UMTS B1 | 24dBm +1/-3dBm | <-110dBm |
| UMTS B2 | 24dBm +1/-3dBm | <-110dBm |
| UMTS B4 | 24dBm +1/-3dBm | 108dBm |
| UMTS B5 | 24dBm +1/-3dBm | <-110dBm |
| UMTS B6 | 24dBm +1/-3dBm | <-110dBm |
| UMTS B8 | 24dBm +1/-3dBm | <-110dBm |
| UMTS B19 | 24dBm +1/-3dBm | <-110dBm |
| FDD-LTE B1 | 23dBm+2/-2dBm | <-97.5dBm |
| FDD-LTE B2 | 23dBm+2/-2dBm | <-98dBm |
| FDD-LTE B3 | 23dBm+2/-2dBm | <-96.5dBm |
| FDD-LTE B4 | 23dBm+2/-2dBm | <-98dBm |
| FDD-LTE B5 | 23dBm+2/-2dBm | <-98dBm |
| FDD-LTE B7 | 23dBm+2/-2dBm | <-95.5dBm |
| FDD-LTE B8 | 23dBm+2/-2dBm | <-98dBm |

| | | |
|-------------|---------------|-----------|
| FDD-LTE B12 | 23dBm+2/-2dBm | <-95dBm |
| FDD-LTE B13 | 23dBm+2/-2dBm | <-95dBm |
| FDD-LTE B14 | 23dBm+2/-2dBm | <-95dBm |
| FDD-LTE B18 | 23dBm+2/-2dBm | <-98dBm |
| FDD-LTE B19 | 23dBm+2/-2dBm | <-98dBm |
| FDD-LTE B20 | 23dBm+2/-2dBm | <-97dBm |
| FDD-LTE B25 | 23dBm+2/-2dBm | <-98dBm |
| FDD-LTE B26 | 23dBm+2/-2dBm | <-98dBm |
| FDD-LTE B28 | 23dBm+2/-2dBm | <-96dBm |
| TDD-LTE B38 | 23dBm+2/-2dBm | <-96.5dBm |
| TDD-LTE B40 | 23dBm+2/-2dBm | <-97dBm |
| FDD-LTE B66 | 23dBm+2/-2dBm | <-98dBm |
| FDD-LTE B71 | 23dBm+2/-2dBm | <-95dBm |



All values above were obtained in the lab. In actual applications, there might be a difference because of network environments.

5.3 GNSS Feature

| Changes | Parameter |
|--------------------------------|---|
| GPS L1 operating frequency | 1575.42±1.023 MHz |
| GLONASS operating frequency | 1597.5~1605.9 MHz |
| BDS operation frequency | 1559.1~1563.1 MHz |
| Tracking sensitivity | -160 dBm (GPS)/-159.5 dBm (GLONASS)/TBD (BDS) |
| Acquisition sensitivity | -144 dBm (GPS)/-143.5 dBm (GLONASS) |
| Positioning precision (in air) | < 3 m (CEP50) |
| Hot start (in air) | <2.5s |
| Cold start (in air) | <35s |
| Update frequency | 1 Hz by default |
| CNR in/CNR out | 3 dB |
| Max. positioning altitude | 18000m |

| | |
|-------------------------------|------------------------|
| Max. positioning speed | 515 m/s |
| Max. positioning acceleration | 4g |
| GNSS data type | NMEA-0183 |
| GNSS antenna type | Passive/active antenna |



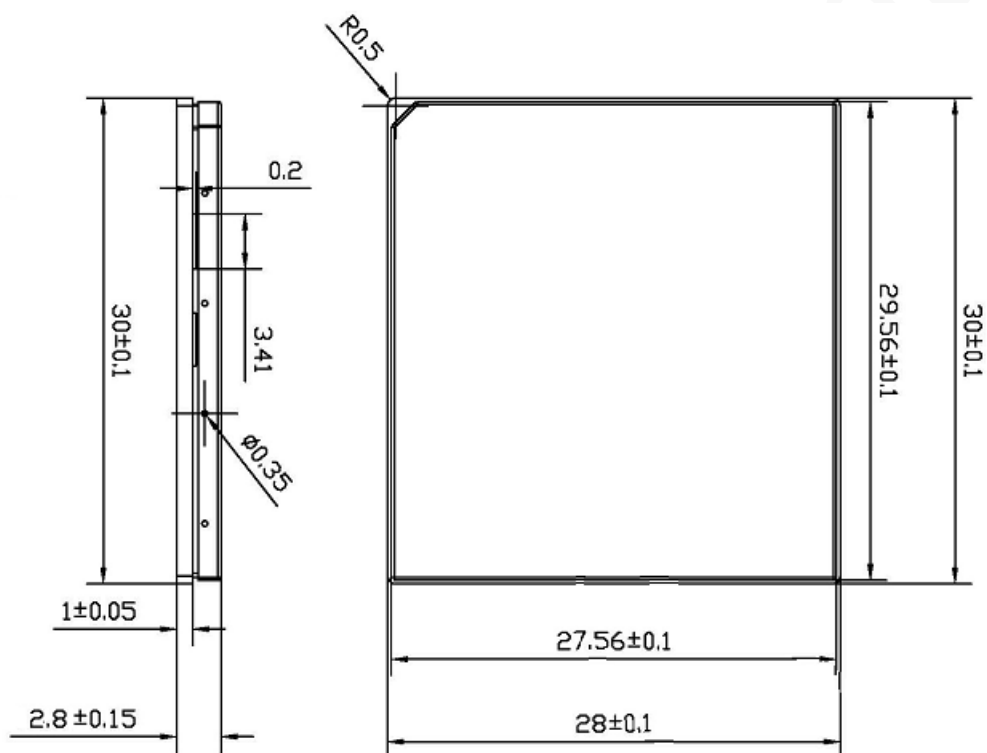
Tracking sensitivity, acquisition sensitivity, and re-acquisition sensitivity were obtained in a signaling test on SPIRENT6300 and they are the maximum values of multiple tests on samples. No external LNA or active antenna was used in the test.

6 Mechanical Features

This chapter describes the mechanical features of the N75.

6.1 Dimensions

Figure 6-1 N75 dimensions



The unit is mm.

6.2 Label

The label is made of materials that are deformation-resistant, fade-resistant, and high-temperature-resistant and it can endure a high temperature up to 260°C.

Figure 6-2 N75 label



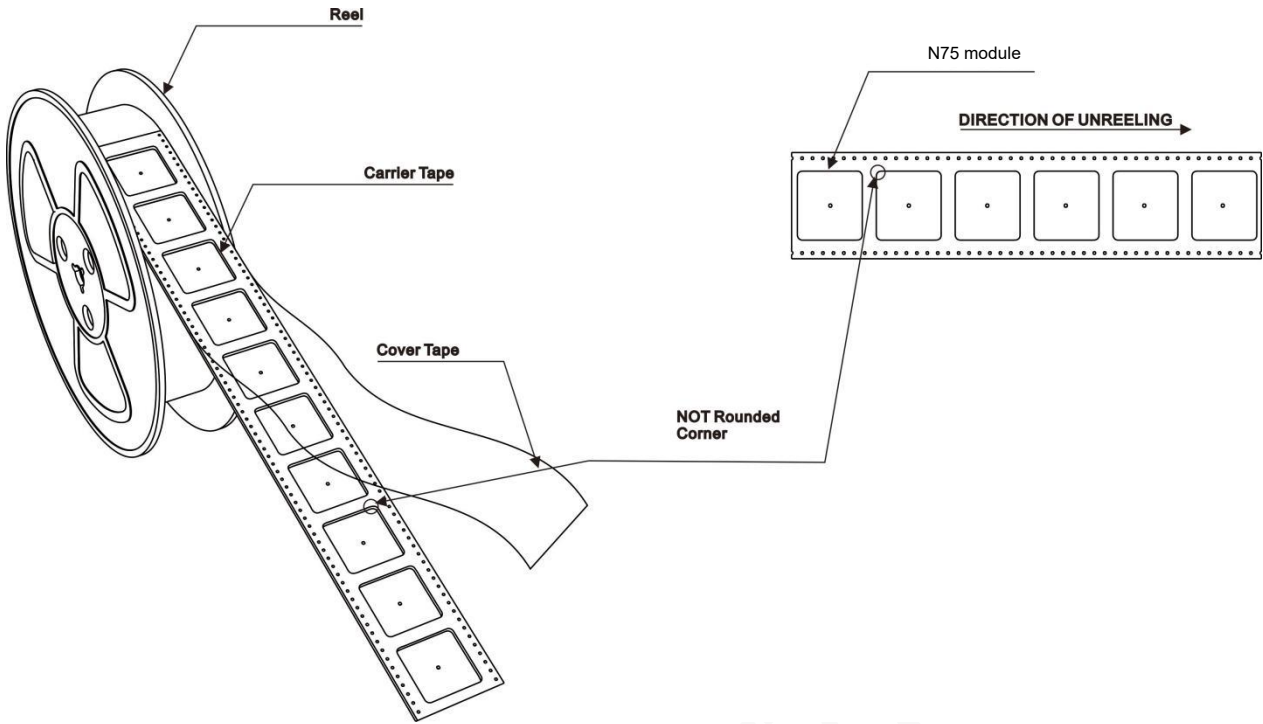
- The picture above is only for reference.
- The silk-screen printing must be clear. No blur is allowed.
- The material and surface finishing must comply with RoHS directives.

6.3 Pack

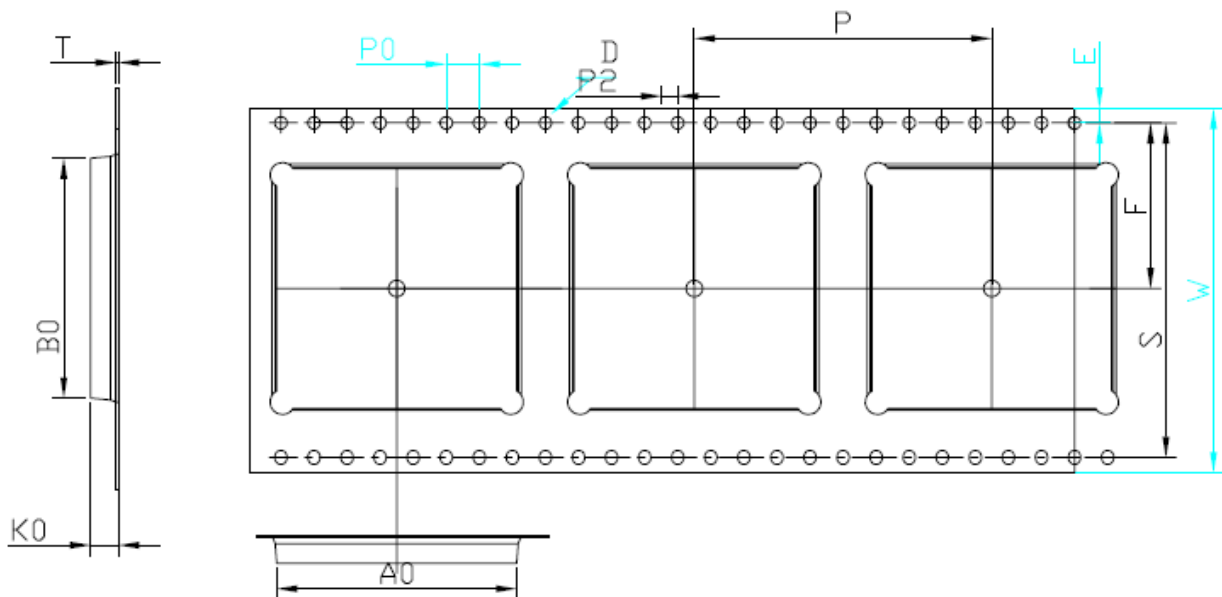
N75 modules are packaged in sealed vacuum bags with dryer, humidity card, and tray on delivery to guarantee a long shelf life. Follow the same package method again in case of opened for any reason.

6.3.1 Reel&Tape

The N75 in mass production is shipped in the following package.

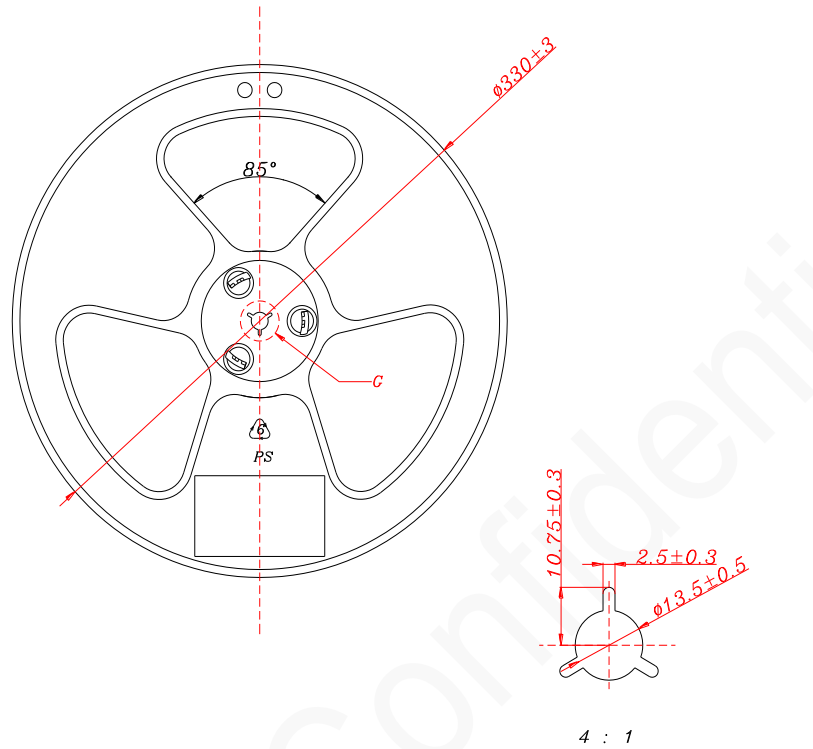


Tape



| ITEM | W | A0 | B0 | S | D | E | F | K0 | P0 | P2 | P | T |
|------|--------------|--------------|--------------|--------------|--------------|------|-------|--------------|------|------|------|-------|
| DIM | 44.0 | 28.7 | 28.70 | 40.4 | 1.5 | 1.75 | 20.2 | 3.55 | 4.0 | 2.0 | 36.0 | 0.30 |
| TOLE | +0.3 -0.3 | +0.1 -0.1 | +0.1 -0.1 | +0.1 -0.0 | +0.1 -0.0 | ±0.1 | ±0.10 | +0.1 -0.1 | ±0.1 | ±0.1 | ±0.1 | ±0.05 |

Reel



6.3.2 Moisture

N75 is a level 3 moisture-sensitive electronic elements, in compliance with IPC/JEDEC J-STD-020 standard.

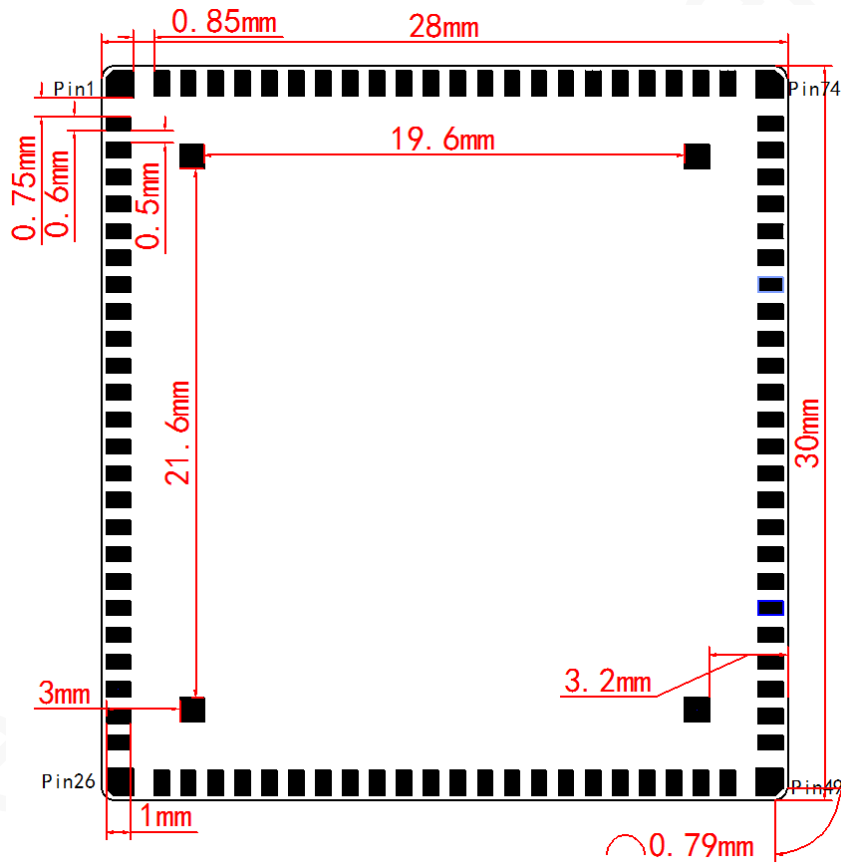
If the module is exposed to air for more than 48 hours at conditions not worse than 30°C/60% RH, bake it at a temperature higher than 90°C for more than 12 hours before SMT. Or, if the indication card shows humidity greater than 20%, the baking procedure is also required. Do not bake modules with the package tray directly.

7 Mounting N75 onto Application Board

N75 is introduced in the 100-pin LGA package. This chapter describes N75V5 footprint, recommended PCB design and SMT information to guide users on how to mount the module onto an application PCB board.

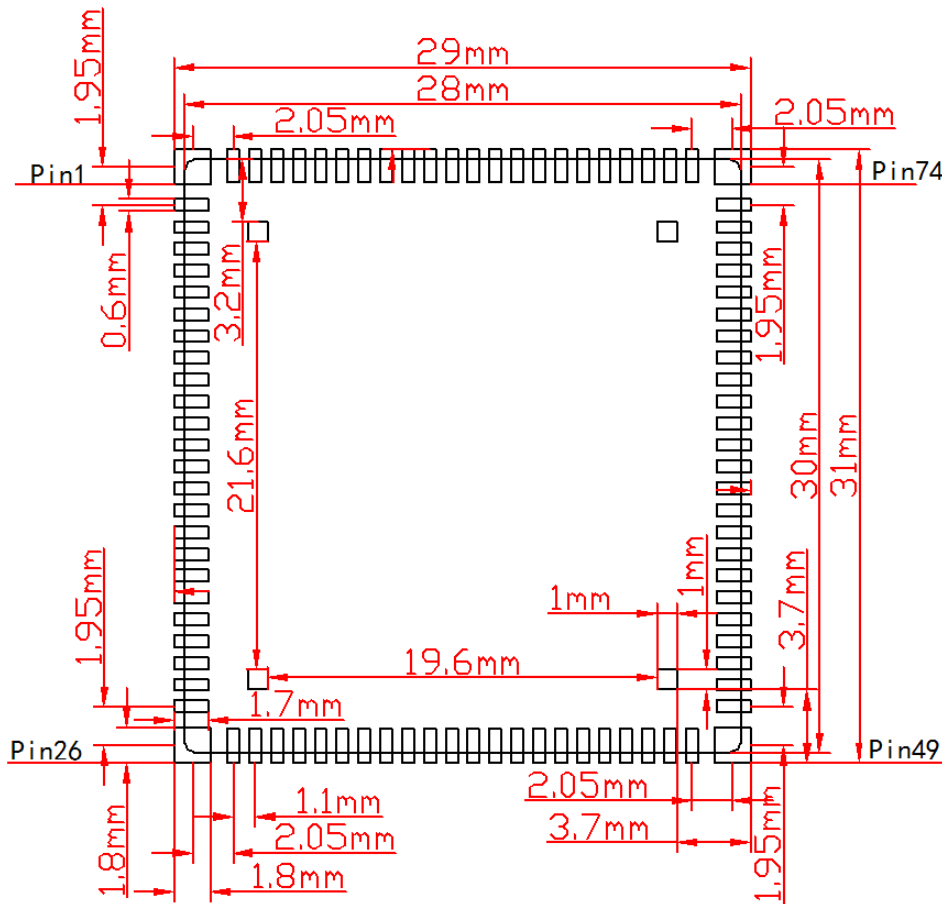
7.1 Bottom Dimensions

Figure 7-1 Bottom view



7.2 Application Foot Print

Figure 7-2 Recommended Application Foot Print (Top View)



7.3 Stencil

The recommended stencil thickness is at least 0.12 mm to 0.15 mm.

7.4 Solder Paste

The quality of the solder joint depends on the solder paste volume and the PCB flatness.

Do not use the kind of solder paste different from our module technique.

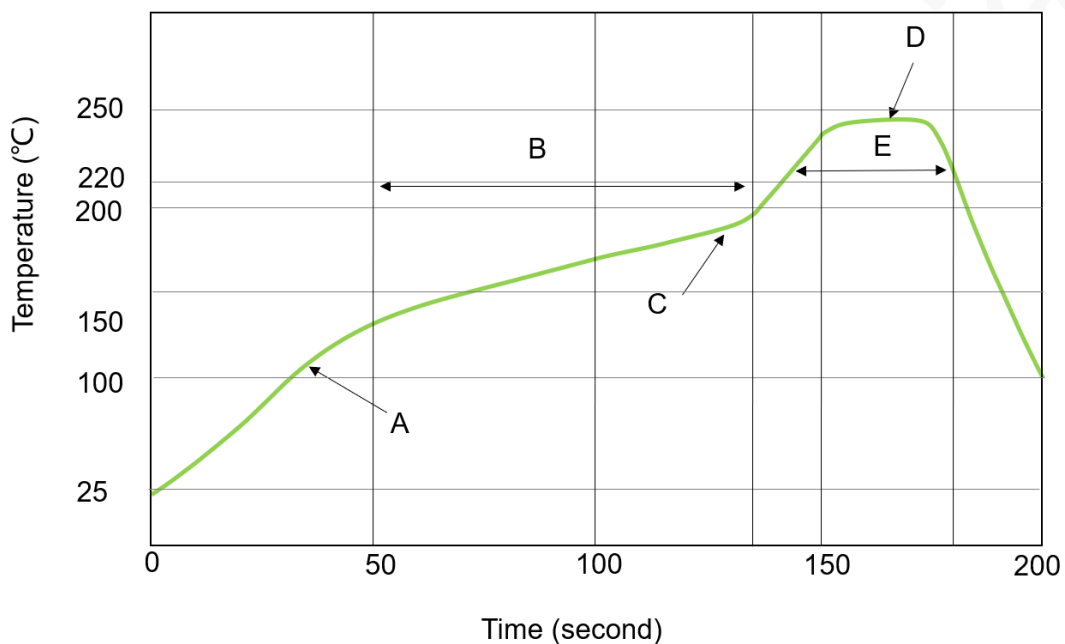
- The melting temperature of solder paste with lead is 35°C lower than that of solder paste without lead. It is easy to cause voiding for LGA and LCC inside the module after reflow soldering for the second time.

- When using only solder pastes with lead, please ensure that the reflow temperature is kept at 220°C for more than 45 seconds and the peak temperature reaches 240°C.

7.5 SMT Furnace Temperature Curve

Thin or long PCB might bend during SMT. So, use loading tools during the SMT and reflow soldering process to avoid poor solder joint caused by PCB bending.

Figure 7-3 SMT furnace temperature curve



Technical parameters:

- Ramp up rate: 1 to 4°C /sec
- Ramp down rate: -3 to -1°C /sec
- Soaking zone: 150-180°C, Time: 60-100 s
- Reflow zone: >220°C, Time: 40-90 s
- Peak temperature: 235-245°C



Neoway will not provide a warranty for heat-responsive element abnormalities caused by improper temperature control.

For information about cautions in N75 storage and mounting, refer to *Neoway Module Reflow Manufacturing Recommendations*.

When manually desoldering the module, use heat guns with great opening, adjust the temperature to 245°C (depending on the type of the solder paste), and heat the module till the solder paste is melt. Then remove the module using tweezers. Do not shake the module in high temperatures while removing it. Otherwise, the components inside the module might get misplaced.

Neoway Confidential

8 Safety Recommendations

Ensure that this product is used in compliance with the requirements of the country and the environment. Please read the following safety recommendations to avoid body hurts or damages of product or workplace:

- Do not use this product at any places with a risk of fire or explosion such as gasoline stations, oil refineries, etc.
- Do not use this product in environments such as hospitals or airplanes where it might interfere with other electronic equipment.

Please follow the requirements below in application design:

- Do not disassemble the module without permission from Neoway. Otherwise, we are entitled to refuse to provide further warranty.
- Please design your application correctly by referring to the HW design guide document and our review feedback on your PCB design. Please connect the product to a stable power supply and layout traces following fire safety standards.
- Please avoid touching the pins of the module directly in case of damages caused by ESD.
- Do not remove the USIM card in idle mode if the module does not support hot-swapping.

A Conformity and Compliance

A.1 Approvals

- FCC
- PTCRB
- AT&T*
- CE-R*
- GCF*
- RoHS*
- NCC*
- RCM*

A.2 American Notice

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

A.2.1 Modify

Changes or modifications made to this equipment, not expressly approved by us or parties authorized by us could void the user's authority to operate the equipment.

A.2.2 FCC Class A Digital Device Notice

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a commercial environment. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

A.2.3 FCC Class B Digital Device Notice

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation.

If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

B Abbreviation

| Abbreviation | English Full Name |
|--------------|---|
| ADC | Analog-Digital Converter |
| bps | Bits per second |
| BLSP | BAM low-speed peripheral |
| DC-HSPA+ | Dual-carrier HSPA+ |
| EDGE | Enhanced GSM |
| EV-DO | Evolution-Data Optimized |
| FDD | Frequency Division Duplex |
| GNSS | Global Navigation Satellite System |
| GPIO | General-Purpose Input/Output |
| GPRS | General Packet Radio Service |
| HSPA+ | High-Speed Packet Access |
| I2C | Interintegrated Circuit |
| I2S | Inter-IC Sound |
| LGA | Land Grid Array |
| LTE | Long-Term Evolution |
| MDIO | Management Data Input/Output |
| PCB | Printed Circuit Board |
| PCM | Pulse-Coded Modulation |
| PM | Power management unit |
| RF | Radio Frequency |
| SDC | Secure Digital Controller |
| SGMII | Serial Gigabit Media Independent Interface |
| SPI | Serial Peripheral Interface |
| TD-SCDMA | Time Division-Synchronous Code Division Multiple Access |
| UART | Universal asynchronous receiver-transmitter |
| USIM | Universal Subscriber Identity Module |
| UMTS | Universal Mobile Telecommunications System |

| | |
|---------|---|
| USB | Universal Serial Bus |
| USB-OTG | Universal serial bus on-the-go |
| WCDMA | Wide-band Code Division Multiple Access |
| WCI | Wireless Coexistence Interface |
| WLAN | Wireless Local Area Network |
